



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20120823001
Upgrade to Moisture Level 2 for select devices
in the SOWB (16DW) package
Information Only**

Date: 8/29/2012
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only. Please see the attachment details for the planned implementation date.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20120823001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ISO1050DW	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20120823001			PCN Date:	08/29/2012
Title:	Upgrade to Moisture Level 2 for select devices in the SOIC (16DW) package				
Customer Contact:	PCN Manager	Phone:	+1(214) 480-6037		Dept: Quality Services
Proposed 1st Ship Date:	08/29/2012		Estimated Sample Availability:	Date provided at sample request	
Change Type:					
<input type="checkbox"/> Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials	
<input type="checkbox"/> Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification	
<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process	
<input type="checkbox"/> Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process	
PCN Details					
Description of Change:					
Informational notification of Upgrade to Moisture Level 2 for select devices in the SOIC (16DW) package. See table below:					
Package		Moisture Sensitivity			
		Change From:	Change To:		
DW		Level 4-260C	Level 2-260C		
Reason for Change:					
Upgrade.					
Anticipated impact on Fit, Form, Function & Reliability (positive / negative):					
None.					
Changes to product identification resulting from this PCN:					
Packing label on bag, box, reel will indicate: "MS LVL: 2"					
Product Affected					
ISO1050DW	ISO1050DWR				

Qualification Data: Approved 03/02/2012

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1 : ISO1050DW (MSL 2-260C)

Package Construction Details

Assembly Site:	TI Taiwan	Mold Compound:	4211470
# Pins-Designator, Family:	16-DW, SOWB	Mount Compound:	4209640
Solder Ball Composition	NiPdAu	Bond Wire:	0.96 Mil Dia., Au

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0
Manufacturability	(per mfg. Site specification)	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0

Notes: * Preconditioning sequence: Level 2-260C.

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com